

DATA SHEET

SKY73010: 300 – 2500 MHz Direct Quadrature Modulator

Applications

- QPSK/GMSK/QAM/DQPSK modulators
- Single-sideband modulators
- Image reject mixers
- CDMA base stations
- GSM/EDGE, TDMA/TDMA-EDGE, and Trans-European Trunked Radio (TETRA) base stations
- First upconverter in dual conversion receivers

Features

- Broad RF and LO frequency range: 300 to 2500 MHz
- Carrier suppression greater than 35 dBc
- Sideband suppression greater than 45 dBc
- Modulation bandwidth DC to 250 MHz
- Noise floor less than -153 dBm/Hz
- Broadband LO/RF flatness
- 16-pin RFLGA™ 4 x 4 mm package

Description

Skyworks' SKY73010 is an integrated quadrature modulator for direct modulation of high frequency Amplitude Modulated (AM), Phase Modulated (PM), or compound carriers. A SiGe Bipolar Complementary Metal Oxide Semiconductor (BiCMOS) process is used to offer excellent linearity, noise floor, and carrier suppression performance.

The device package and pinout for the 16-pin RF Land Grid Array (RFLGA) are shown in Figure 1. Figure 2 shows a functional block diagram for the SKY73010. Signal pin assignments and functional pin descriptions are provided in Table 1.

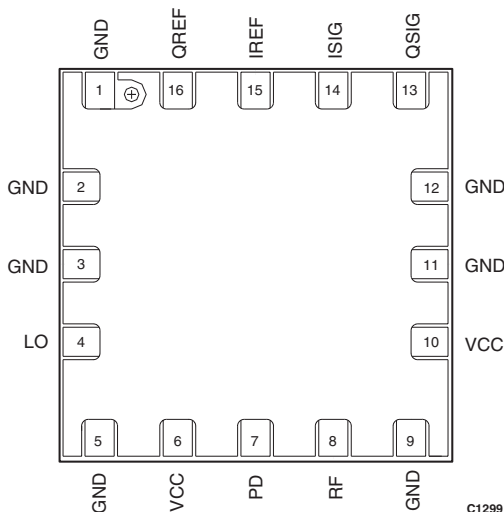


Figure 1. SKY73010 Pinout– 16-Pin RFLGA Package (Top View)

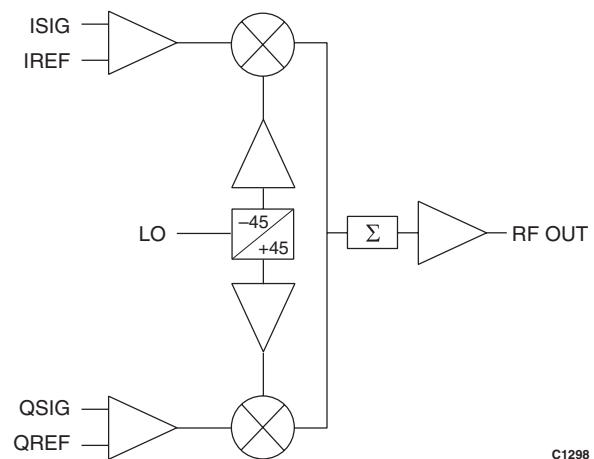


Figure 2. SKY73010 Functional Block Diagram

Table 1. SKY73010 Signal Descriptions

Pin #	Name	Description	Pin #	Name	Description
1	GND	Ground	9	GND	Ground
2	GND	Ground	10	VCC	+5 VDC supply
3	GND	Ground	11	GND	Ground
4	LO	LO input	12	GND	Ground
5	GND	Ground	13	QSIG	Q input
6	VCC	+5 VDC supply	14	ISIG	I input
7	PD	Power down	15	IREF	I reference
8	RF	Ground	16	QREF	Q reference

Circuit Design Considerations

The following design considerations are general in nature and must be followed regardless of final use or configuration.

1. Paths to ground should be made as short as possible.
2. The downset paddle of the SKY73010 direct quadrature modulator has special electrical and thermal grounding requirements. This pad is the main thermal conduit for heat dissipation. Since the circuit board acts as the heat sink, it must shunt as much heat as possible from the device. As such, design the connection to the ground pad to dissipate the maximum wattage produced to the circuit board. Multiple vias to the grounding layer are required.
3. Two external output bypass capacitors are required on the VCC pin. The values of these capacitors change with respect to the desired RF frequency. One capacitor should be used for low frequency bypassing and the other capacitor for high frequency bypassing. Special attention should be given so that the smaller value capacitor does not go into self-resonance at the desired RF frequency.

Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

If the part is attached in a reflow oven, the temperature ramp rate should not exceed 10 °C per second. Maximum temperature should not exceed 225 °C and the time spent at a temperature that exceeds 210 °C should be limited to less than 10 seconds. If the part is manually attached, precaution should be taken to ensure that the part is not subjected to a temperature that exceeds 300 °C for more than 10 seconds.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format. For packaging details, refer to the Skyworks' Application Note, *Tape and Reel*, document number 101568.

Electrical and Mechanical Specifications

The absolute maximum ratings of the SKY73010 are provided in Table 2. The recommended operating conditions are specified in Table 3 and electrical specifications are provided in Table 4.

Figure 3 provides the package dimensions for the 16-pin RFLGA and Figure 4 provides the tape and reel dimensions.

Electrostatic Discharge (ESD) Sensitivity

The SKY73010 is a static-sensitive electronic device. Do not operate or store near strong electrostatic fields. Take proper ESD precautions.

Table 2. SKY73010 Absolute Maximum Ratings
(T_A = +25 °C, unless otherwise noted)

Parameter	Symbol	Min	Typical	Max	Units
+3 V supply voltage	VCC	4.5		6.0	V
Power dissipation	P _{DIS}			750	mW
LO input power	P _{LOIN}		0	+6	dBm
IF input voltage				1.5	V _{pp}
Thermal resistance	R _{TH}		44		°C/W
Operating case temperature	T _{OPR}	−40		+85	°C
Storage case temperature	T _{STG}	−40		+150	°C

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal values.

Table 3. SKY73010 Recommended Operating Conditions

Parameter	Symbol	Min	Typical	Max	Units
+5 V supply voltage	VCC	4.5	5.0	5.5	V
Current consumption	I _{CC}		90	110	mA
Operating case temperature	T _{OPR}	−40		+85	°C

Table 4. SKY73010 Electrical Characteristics (1 of 2)

(VCC = 5 V, IF = 2 MHz, LO input power = 0 dBm, T_c = 25 °C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typical	Max	Units
Local Oscillator						
Input frequency range			300		2500	MHz
Input power level			−3		+3	dBm
Input impedance				2.0:1		VSWR
I/Q Signal Reference Input						
Input frequency range			DC		250	MHz
Reference voltage			3.6	4.1		V
RF Output (400 MHz)						
Output −1 dB compression point				3		dBm
CDMA output channel power				−12		dBm
CDMA ACPR		CDMA RF output power = −12 dBm		73		dBc
Optimized carrier suppression		Optimized I/Q DC offsets	50			dBc
Carrier suppression			28	35		dBc
Sideband suppression			30	35		dBc
Optimized sideband suppression		Optimized I/Q phase and amplitude balance	50			dBc
Broadband noise floor		@ 20 MHz offset from carrier		−152	−150	dBm/Hz
Output impedance				2.0:1		Ω

Table 4. SKY73010 Electrical Characteristics (2 of 2)**(VCC = 5 V, IF = 2 MHz, LO input power = 0 dBm, Tc = 25 °C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typical	Max	Units
RF Output (900 MHz)						
Output –1 dB compression point				1.8		dBm
CDMA output channel power				–12		dBm
CDMA ACPR		CDMA RF output power = –12 dBm		72		dBc
Optimized carrier suppression		Optimized I/Q DC offsets	50			dBc
Carrier suppression			28	35		dBc
Sideband suppression			35	45		dBc
Optimized sideband suppression		Optimized I/Q phase and amplitude balance	50			dBc
Broadband noise floor		@ 20 MHz offset from carrier		–153	–151	dBm/Hz
Output impedance				2.0:1		Ω
RF Output (1900 MHz)						
Output –1 dB compression point				–3.5		dBm
CDMA output channel power				–18		dBm
CDMA ACPR		CDMA RF output power = –18 dBm		70		dBc
Optimized carrier suppression		Optimized I/Q DC offsets		50		dBc
Carrier suppression			22	28		dBc
Sideband suppression			28	35		dBc
Optimized sideband suppression		Optimized I/Q phase and amplitude balance		50		dBc
Broadband noise floor		@ 20 MHz offset from carrier		–155	–153	dBm/Hz
Output impedance				2.0:1		Ω

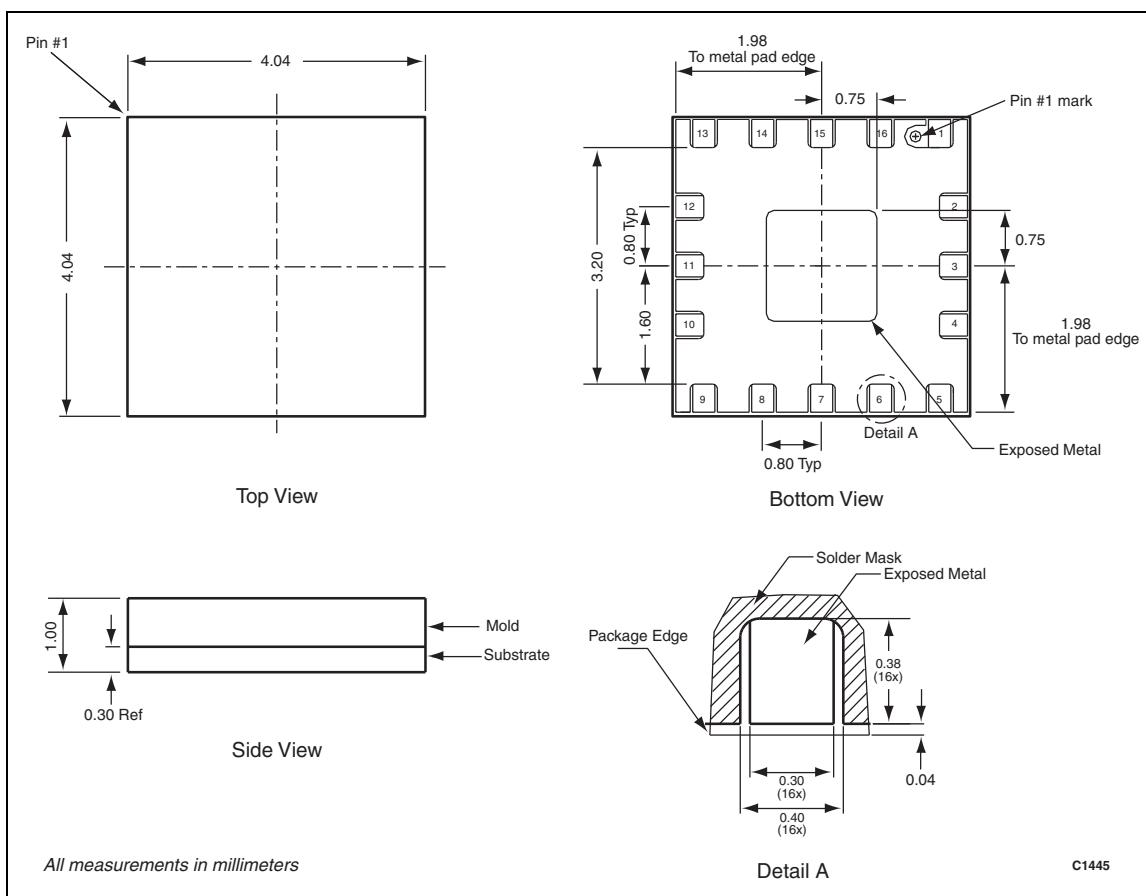


Figure 3. SKY73010 16-Pin RFLGA Package Dimensions

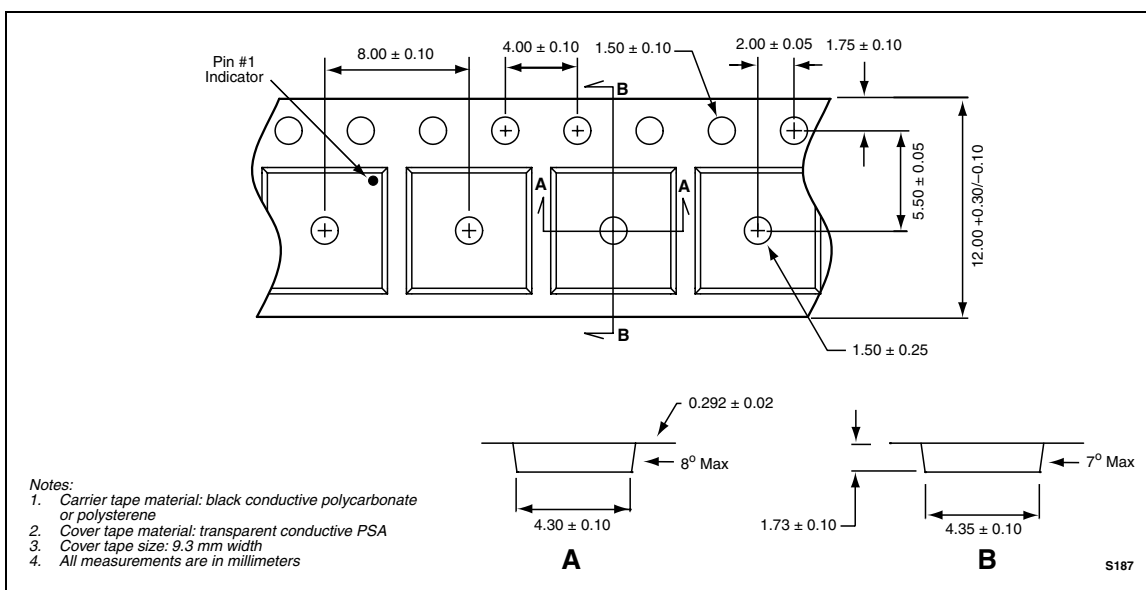


Figure 4. SKY73010 16-Pin RFLGA Tape and Reel Dimensions

Ordering Information

Model Name	Manufacturing Part Number	Evaluation Kit Part Number
SKY73010 300-2500 MHz Direct Quadrature Modulator	SKY73010-11	TW12-D692

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